IoTGW
Isolation module

BOARD CHARACTERISTICS

Copper Layer Count:	2	Board Thickness:	1,6000 mm
Board overall dimensions:	40,0000 mm x 48,5000 mm	Via size: 0,7mm Pad / 0,3mm Hole	
Min track/spacing:	0,1600 mm / 0,2000 mm	Min hole diameter:	0,1000 mm
Copper Finish:	None	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0,01 mm	Not specified	3,3	0
F.Cu	copper		0,035 mm		1	0
Dielectric 1	core	FR4	1,51 mm	FR4 natural	4,5	0,02
B.Cu	copper		0,035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0,01 mm	Not specified	3,3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

Sheet:
File: IoTGW_Isolation.kicad_pcb

Title: IoTGW Galvanic Isolation

Size: A4	Date: 2025−01−24	Rev: v3.0.0
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